

ABSTRACT

An enclosure for electronic components is provided. The enclosure includes an electronics housing that has at least one slot for receiving one or more electronic components. The slot is defined by a plurality of walls. A heat pipe thermal management system is associated with the slot. The heat pipe system includes a heat pipe having a first portion embedded into one of the walls defining the slot for conducting heat from the wall to a second portion of the heat pipe extending out of the electronics housing. At least one cooling fin is carried by the second portion of the heat pipe such that heat from the heat pipe is conducted into the fin and the fin dissipates the heat to the ambient atmosphere outside of the electronics housing.